

Notice of References Cited	Application/Control No. 10/708,642	Applicant(s)/Patent Under Reexamination CHUANG ET AL.	
	Examiner Patricia A. George	Art Unit 1765	Page 1 of 1

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	U	Wilson, 1993, William Andrews/Noyes, Handbook of Multilevel metalization for Integrated Circuits - Materials, Technology, and Applications; pg 149-150
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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